

Title (en)
ELECTRICALLY CONDUCTIVE FLOOR CONSTRUCTION

Publication
EP 0228004 A3 19881130 (DE)

Application
EP 86117324 A 19861212

Priority
DE 3545760 A 19851221

Abstract (en)
[origin: US4770916A] An electrically conductive flooring and method for constructing same upon an existing flooring, which comprises sequential layers of: a nonwoven base layer; an electrically conductive coating layer; an electrically conductive adhesive layer; and an antistatic or electrically conductive top layer; a copper band is optionally located within the coating layer and/or adhesive layer.

IPC 1-7
H05F 3/02; E04F 15/16; E04F 15/02

IPC 8 full level
E04F 15/02 (2006.01); **E04F 15/16** (2006.01); **H05F 3/02** (2006.01)

CPC (source: EP US)
E04F 15/02 (2013.01 - EP US); **H05F 3/025** (2013.01 - EP US); **Y10T 428/1424** (2015.01 - EP US); **Y10T 428/23979** (2015.04 - EP US); **Y10T 428/24917** (2015.01 - EP US); **Y10T 428/30** (2015.01 - EP US); **Y10T 442/2861** (2015.04 - EP US); **Y10T 442/697** (2015.04 - EP US)

Citation (search report)
• [A] US 4301040 A 19811117 - BERBECO GEORGE R
• [A] DE 1790224 A1 19720120 - GAISER KURT, et al
• [A] CH 626938 A5 19811215 - SEMPERIT AG [AT]

Cited by
EP3628788A1

Designated contracting state (EPC)
AT BE CH DE FR GB IT LI LU NL SE

DOCDB simple family (publication)
EP 0228004 A2 19870708; **EP 0228004 A3 19881130**; **EP 0228004 B1 19920122**; AT E72086 T1 19920215; DE 3545760 A1 19870625; DE 3545760 C2 19891005; DE 3683616 D1 19920305; US 4770916 A 19880913

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